

# Innovating Energy Technology

http://www.fujielectric.com/products/semiconductor/ **FUJI POWER MOSFET** 

## **Super J-MOS series**

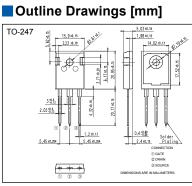
## N-Channel enhancement mode power MOSFET

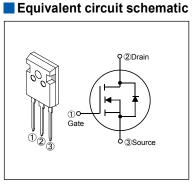
## Features

Pb-free lead terminal **RoHS** compliant uses Halogen-free molding compound

### Applications

For switching





## Absolute Maximum Ratings at Tc=25°C (unless otherwise specified)

Parameter	Symbol	Characteristics	Unit	Remarks
Drain Source Voltage	VDS	600	V	
Drain-Source Voltage	VDSX	600	V	V <sub>GS</sub> =-30V
Continuous Drain Current	lo	±47	А	Tc=25°C Note*1
		±29.7	А	Tc=100°C Note*1
Pulsed Drain Current	DP	±141	А	
Gate-Source Voltage	V <sub>GS</sub>	±30	V	
Repetitive and Non-Repetitive Maximum Avalanche Current	lar	9.5	А	Note *2
Non-Repetitive Maximum Avalanche Energy	Eas	1267.4	mJ	Note *3
Maximum Drain-Source dV/dt	dV <sub>DS</sub> /dt	50	kV/µs	V <sub>DS</sub> ≤ 600V
Peak Diode Recovery dV/dt	dV/dt	13	kV/µs	Note *4
Peak Diode Recovery -di/dt	-di/dt	80	A/µs	Note *5
Maximum Dawar Disainstian	D	2.5	W	T₂=25°C
Maximum Power Dissipation	P₀	390	vv	T₀=25°C
One setting and Starson Temperature range	Tch	150	°C	
Operating and Storage Temperature range	Tstg	-55 to +150	°C	

Note \*1 : Limited by maximum channel temperature. Note \*2 : Tch≤150°C, See Fig.1 and Fig.2 Note \*3 : Starting Tch=25°C, IAs=7.6A, L=40.2mH, Vbb=60V, RG=50Ω, See Fig.1 and Fig.2

EAs limited by maximum channel temperature and avalanche current. Note \*4 : Ir≤23.5A, -di/dt=80A/µs, Vbb≤300V, Tch≤150°C.

Note \*5 : IF≤23.5A, dV/dt=13kV/µs, VDD≤300V, Tch≤150°C.

#### Electrical Characteristics at T<sub>c</sub>=25°C (unless otherwise specified) Static Ratings

Parameter	Symbol	Conditions		min.	typ.	max.	Unit
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	I <sub>D</sub> =250μA V <sub>GS</sub> =0V		600	-	-	V
Gate Threshold Voltage	V <sub>GS(th)</sub>	I <sub>D</sub> =250µA V <sub>DS</sub> =V <sub>GS</sub>		2.5	3.0	3.5	V
Zero Gate Voltage Drain Current	loss	V <sub>DS</sub> =600V V <sub>GS</sub> =0V	T <sub>ch</sub> =25°C	-	-	25	- μA
		V <sub>DS</sub> =480V V <sub>GS</sub> =0V	T <sub>ch</sub> =125°C	-	-	250	
Gate-Source Leakage Current	lass	V <sub>GS</sub> = ± 30V V <sub>DS</sub> =0V		-	10	100	nA
Drain-Source On-State Resistance	RDS(on)	ID=23.5A VGS=10V		-	0.059	0.07	Ω
Gate resistance	RG	f=1MHz, open drain		-	1.1	-	Ω

#### Dynamic Ratings

Parameter	Symbol	Conditions	min.	typ.	max.	Unit
Forward Transconductance	<b>g</b> <sub>fs</sub>	I <sub>D</sub> =23.5A V <sub>DS</sub> =25V	19	38	-	S
Input Capacitance	Ciss	V <sub>DS</sub> =10V	-	4000	-	
Output Capacitance	Coss	V <sub>GS</sub> =0V	-	8400	-	
Reverse Transfer Capacitance	Crss	f=1MHz	-	770	-	
Effective output capacitance, energy related (Note *6)	C <sub>o(er)</sub>	V <sub>GS</sub> =0V V <sub>DS</sub> =0480V	-	210	-	pF
Effective output capacitance, time related (Note *7)	C <sub>o(tr)</sub>	V <sub>GS</sub> =0V V <sub>DS</sub> =0480V ID=constant	-	790	-	
Tum On Time	t <sub>d(on)</sub>		-	36	-	
Turn-On Time	tr	V <sub>DD</sub> =400V, V <sub>GS</sub> =10V	-	83	-	ns
Turn Off Time	t <sub>d(off)</sub>	l₀=23.5A, R₀=8.2Ω See Fig.3 and Fig.4	-	135	-	
Turn-Off Time	tr		-	17	-	
Total Gate Charge	QG	V₀₀=480V, l₀=47A V₀s=10V See Fig.5	-	125	-	nC
Gate-Source Charge	Q <sub>GS</sub>		-	29	-	
Gate-Drain Charge	QGD		-	46	-	
Drain-Source crossover Charge	Qsw		-	18	-	

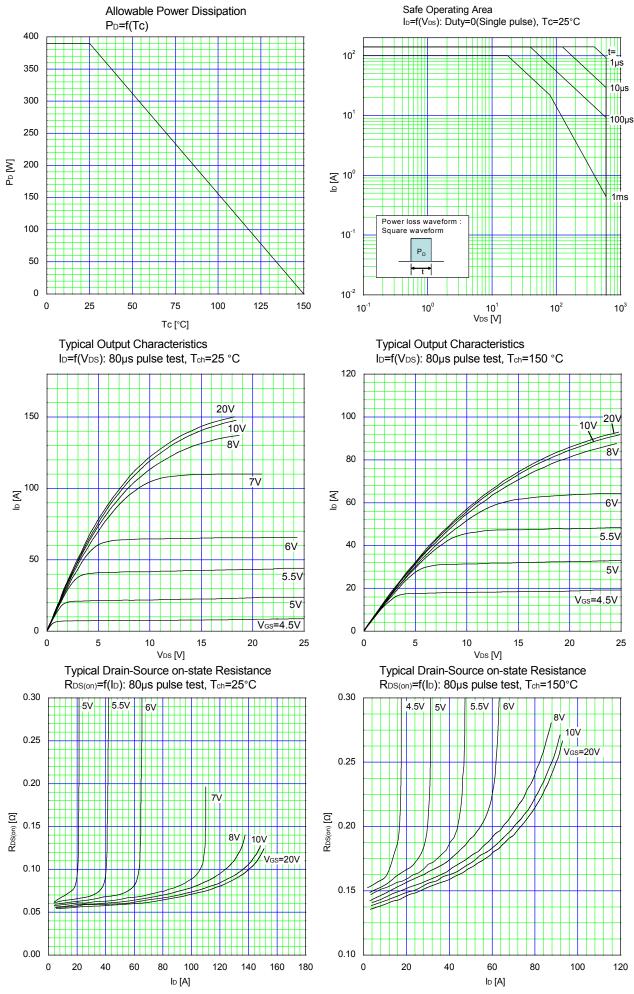
Note \*6 :  $C_{o(er)}$  is a fixed capacitance that gives the same stored energy as  $C_{oss}$  while  $V_{Ds}$  is rising from 0 to 80% BV<sub>Dss</sub>. Note \*7 :  $C_{o(tr)}$  is a fixed capacitance that gives the same charging times as  $C_{oss}$  while  $V_{Ds}$  is rising from 0 to 80% BV<sub>Dss</sub>.

#### Reverse Diode

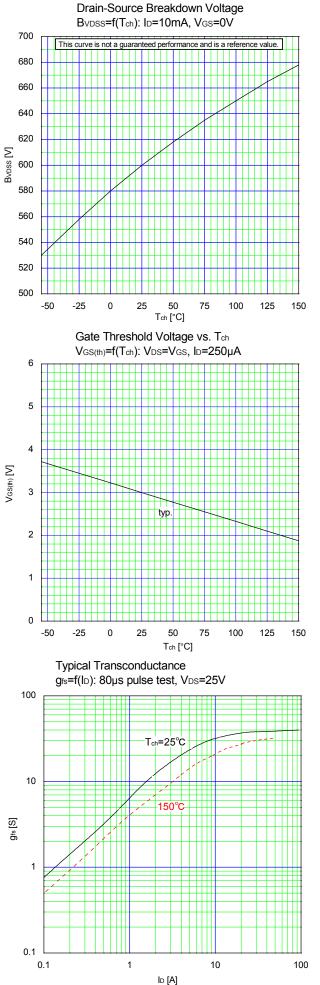
Parameter	Symbol	Conditions	min.	typ.	max.	Unit
Avalanche Capability	lav	L=20.6mH, T₀₁=25°C See Fig.1 and Fig.2	9.5	-	-	А
Diode Forward On-Voltage	V <sub>SD</sub>	I⊧=47A, V₀s=0V T₀h=25°C	-	1.0	1.35	V
Reverse Recovery Time	trr	I⊧=23.5A, V <sub>GS</sub> =0V V <sub>DD</sub> =300V -di/dt=80A/µs T <sub>ch</sub> =25°C See Fig.6		470	-	ns
Reverse Recovery Charge	Qrr		-	8.7	-	μC
Peak Reverse Recovery Current	Ігр		-	36	-	А

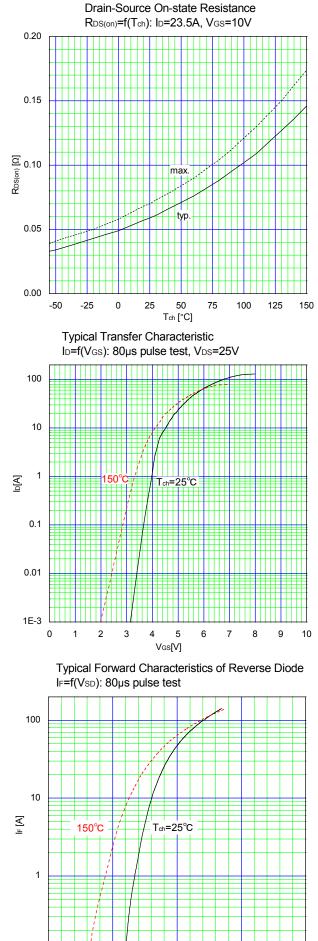
## Thermal Resistance

Parameter	Symbol	min.	typ.	max.	Unit
Channel to Case	Rth(ch-c)	-	-	0.32	°C/W
Channel to Ambient	Rth(ch-a)	-	-	50	°C/W



3





0.1

0.0

0.5

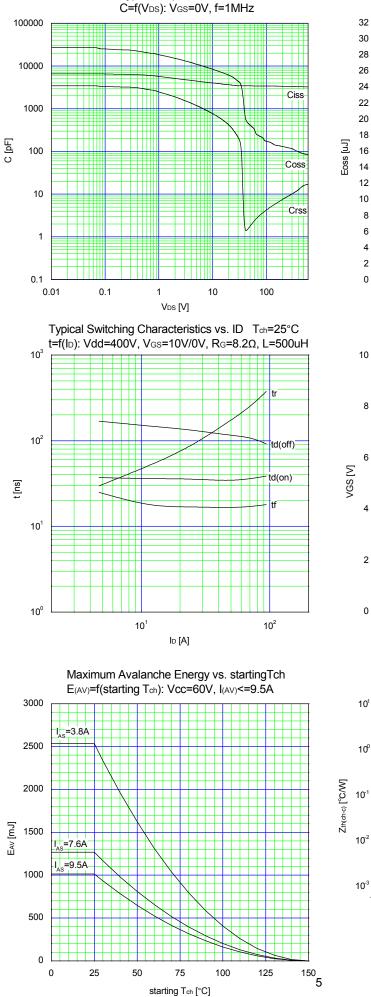
1.0

VSD [V]

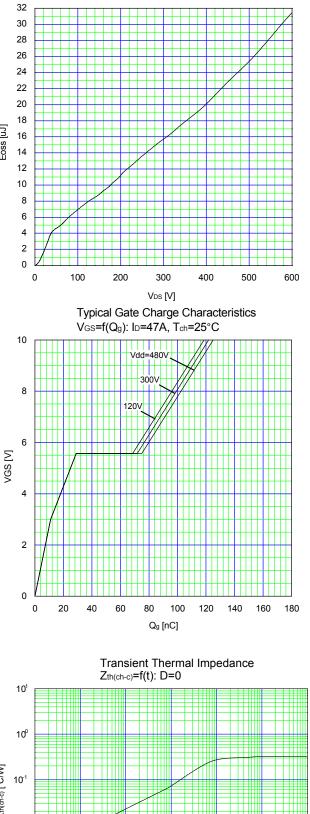
1.5

2.0

Typical Coss stored energy



**Typical Capacitance** 



10<sup>-6</sup>

10<sup>-5</sup>

10-4

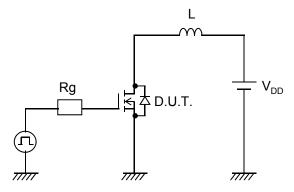
10<sup>-3</sup>

t [sec]

10<sup>-2</sup>

10<sup>-1</sup>

10<sup>0</sup>





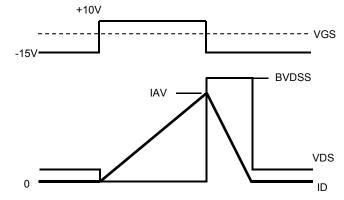


Fig.2 Operating waveforms of Avalanche Test

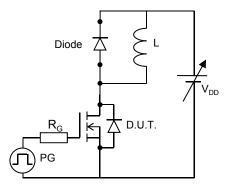


Fig.3 Switching Test circuit

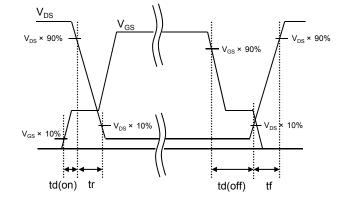


Fig.4 Operating waveform of Switching Test

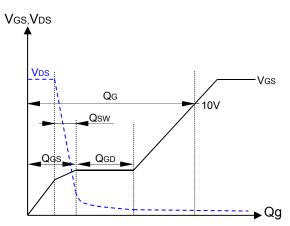


Fig.5 Operating waveform of Gate charge Test

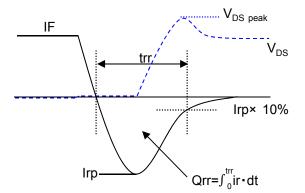
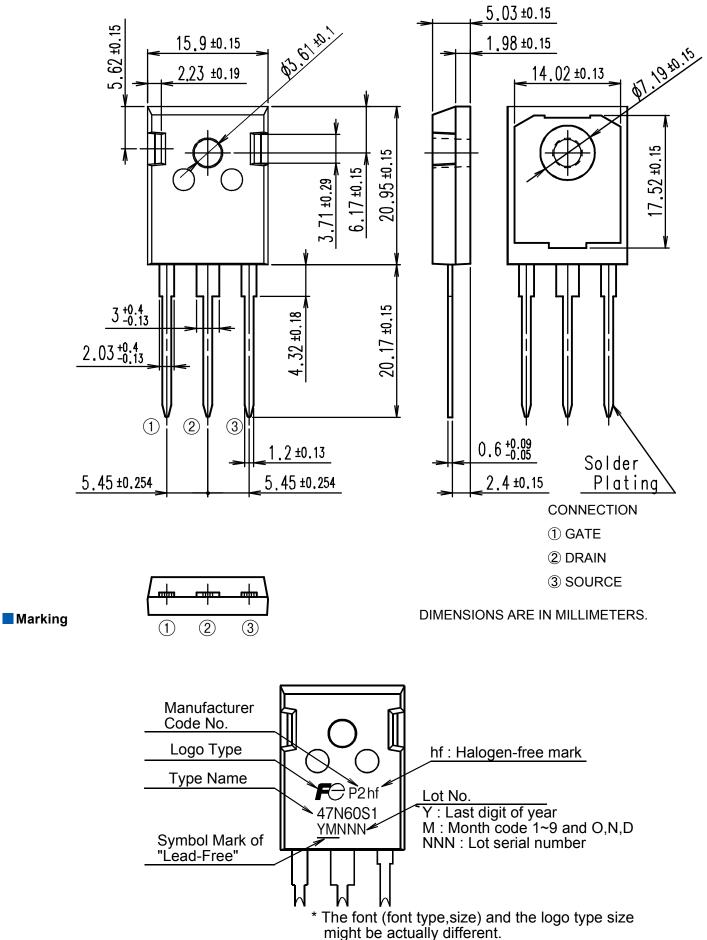


Fig.6 Operating waveform of Reverse recovery Test

## Outview: TO-247 Package



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